International Conference and Exhibition on

Device Packaging

www.imaps.org/devicepackaging

Radisson Fort McDowell Resort & Casino
Scottsdale/Fountain Hills, Arizona - USA
March 9 - 12, 2009

Sponsored by
IMAPS
International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!

Abstract Deadline Extended:
December 5, 2008

Announcement and Call for Abstracts

Topical Workshop on

Wafer Level Chip Scale Packaging (WLCSP)

This workshop is being held as a part of the Device Packaging Conference

Technical Chairs:

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Wafer Level Chip Scale Packaging Organizing Committee:

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Wafer Level Chip Scale Packaging Workshop Focus: The objective of the Wafer Level Chip Scale Packaging Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Wafer Level Chip Scale Packaging (WLCSP). This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to these new packaging technologies.
Abstracts are being requested on the following topics:

- Chip Scale Packaging (CSP and WLCSP)
- Wafer Bumping Materials (UBM, Solder, RDL & Repassivation
- Manufacturing Processes
- Assembly Processes
- Reliability
- Mechanical Testing: (Drop Test, High Speed Pull, Vibration, Shear...)
- Modeling (Thermal and Mechanical)
- End use applications (i.e., OEM products)

Those wishing to present in the Wafer Level Chip Scale Packaging sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **no later than December 5, 2008**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to six-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 30, 2009. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Wafer Level Chip Scale Packaging. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 4, 2009 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 9th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than December 5, 2008.**